



Product End-of-Life Disassembly Instructions

Product Category: Servers

Marketing Name / Model

[List multiple models if applicable.]

HP ProLiant XL220a Gen8 v2 Server

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	8
Batteries	All types including standard alkaline and lithium coin or button style batteries	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	*If FBWC Super Caps are installed.	4
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

Components, parts and materials containing radioactive substances		0
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2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx Screw Driver	T-10
Trox Screw Driver	T-15
Flat Head Screw Driver	Medium
Description #4	
Description #5	

3.0 Product Disassembly Process

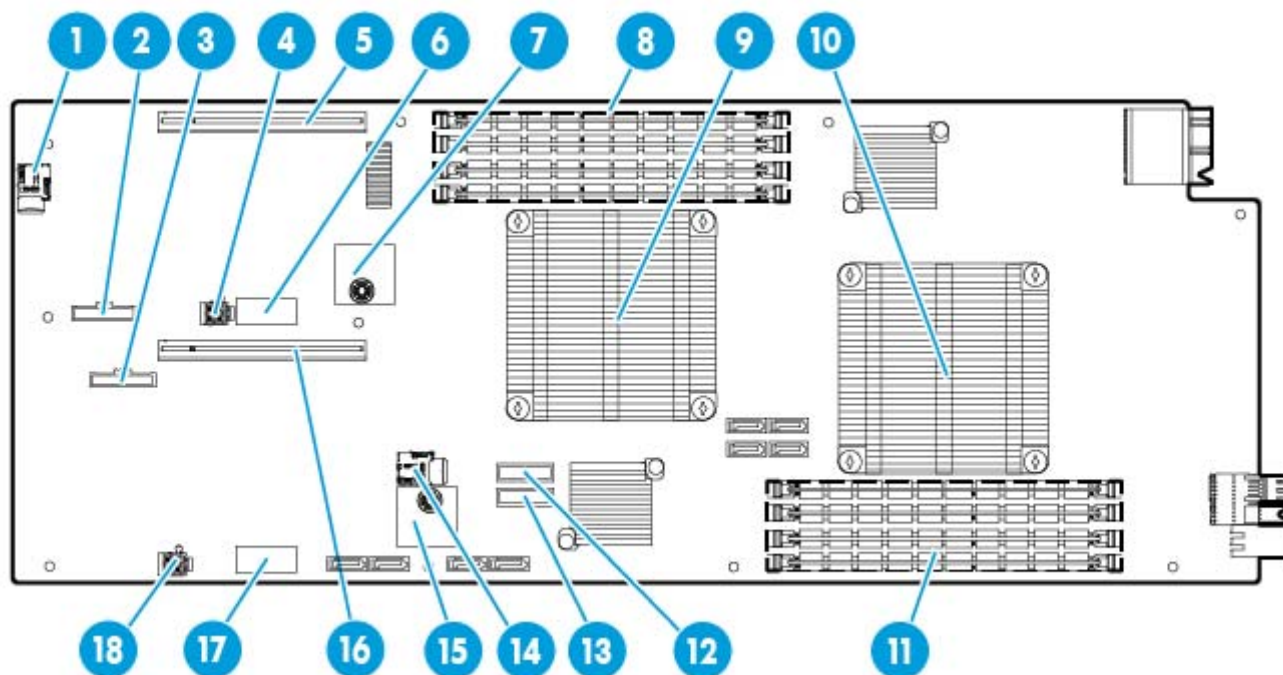
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. System Board Battery - Remove the server tray from the enclosure and locate the batteries on the system board (see Attachment 1, locations 12 & 13). Remove batteries (see Attachment 2 for removal sequence).
2. Flash Back Write Cache (FBWC) Super Cap - Remove the server tray from the enclosure and locate the FBWC super cap cables and capacitors (see Attachment 3). Disconnect cable from FBWC module (see Attachment 4). Remove super caps (see Attachment 5 for removal sequence).
- 3.
- 4.
- 5.
- 6.
- 7.
- 8.

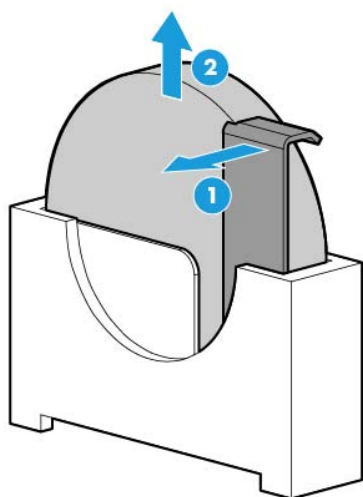
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Attachment 1 – Battery Locations
Attachment 2 – Battery Removal Sequence
Attachment 3 – Flash Back Write Cache (FBWC) Cable and Super Cap Location
Attachment 4 – Flash Back Write Cache (FBWC) Super Cap Cable Removal
Attachment 5 – Flash Back Write Cache (FBWC) Super Cap Removal

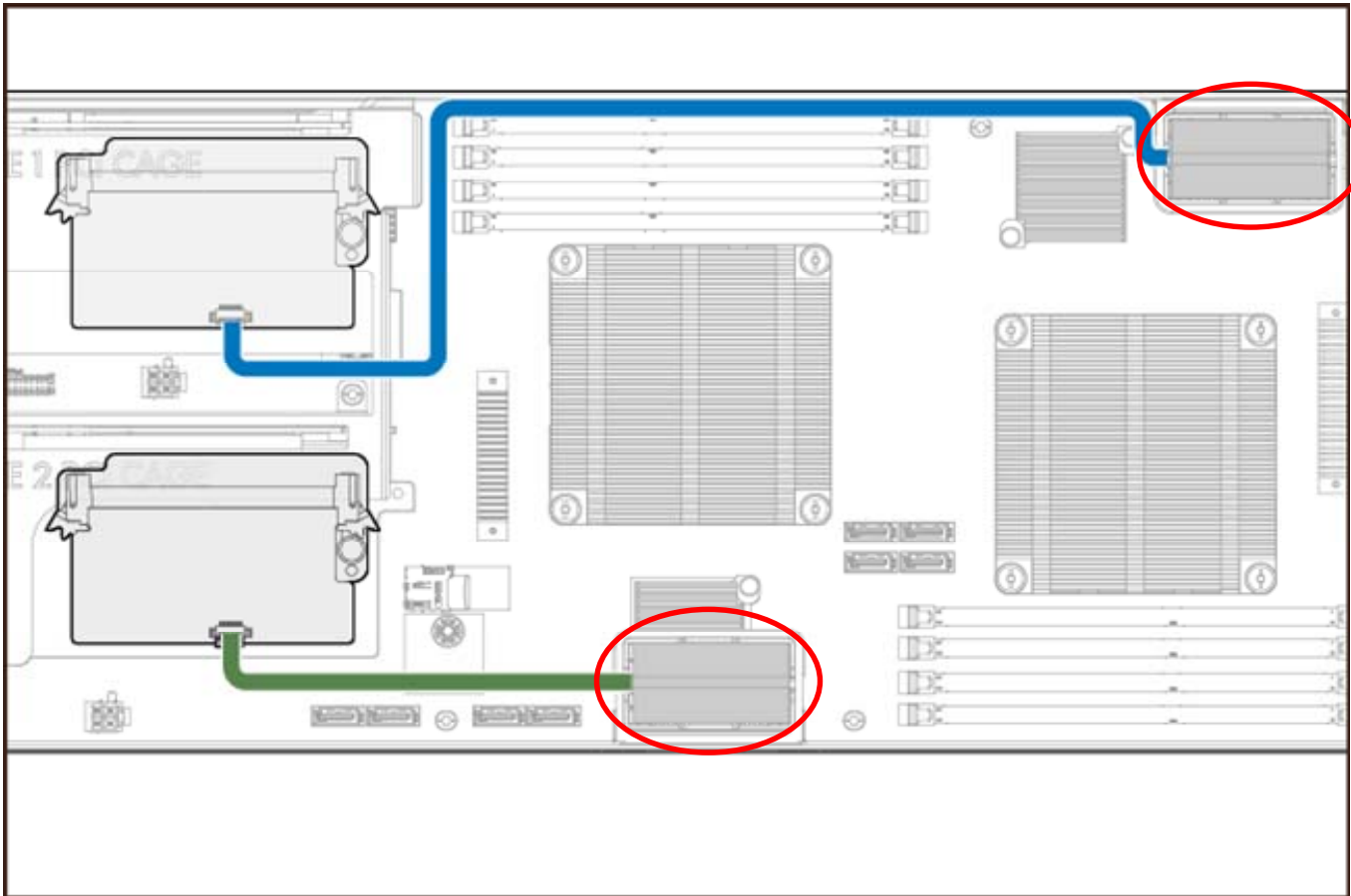
Attachment 1 – Battery Locations (Locations 12 & 13)



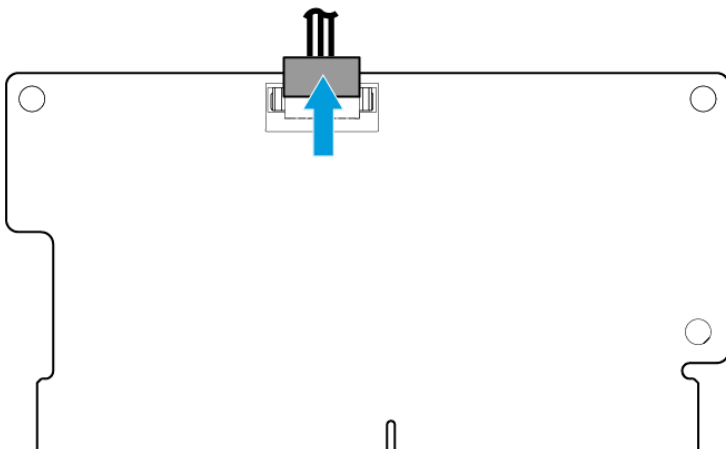
Attachment 2 – Battery Removal Sequence



Attachment 3 – Flash Back Write Cache (FBWC) Cable and Super Cap Location



Attachment 4 – Flash Back Write Cache (FBWC) Super Cap Cable Removal



Attachment 5 – Flash Back Write Cache (FBWC) Super Cap Removal

